



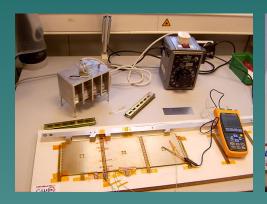


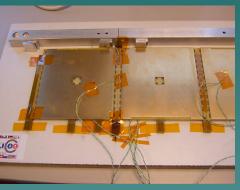
Status / plans of ASU interconnections

part 1 : Define the time for ASU interconnection

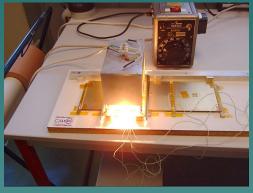
part 2 : Next steep

part 1 : Define the time for ASU interconnection



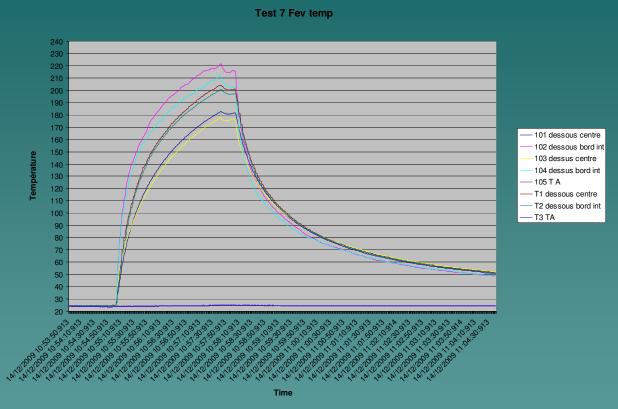






Test with Fev temp cards and Cambridge's lamp controled by 2 instruments: Fluke data logger and Agilent 34970A

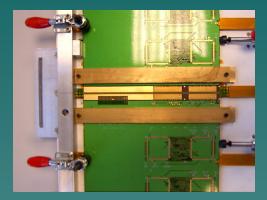
part 1: Define the time for ASU interconnection



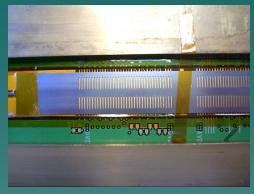
Results of test

- 1 maximum heat for 3 minutes to 200 degrees Celsius
- 2 voltage stabilized with Variac at 200 volts during 15 seconds

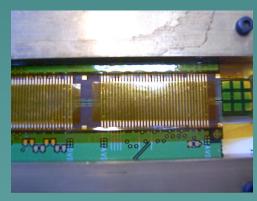
Interconnection performed on two FEV 7 CIP



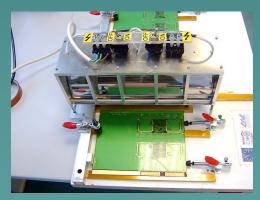
2 cards FEV7 CIP on soldering bench



Raises the Screen printing on board

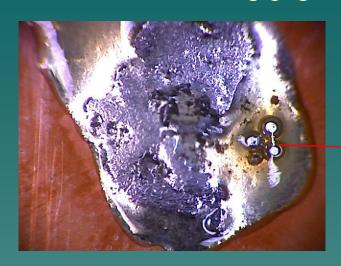


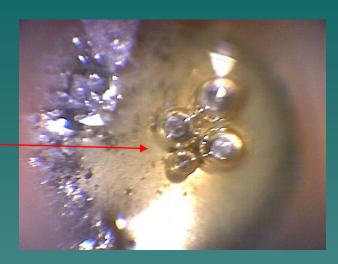
Raises the kapton connectors



Set up for the lamp

Problems encountered





-This problem of bubbles in the solder arising from a lowering of the temperature at the end of solder too long, this necessitates to use of a ventilation untite

-And another problem when soldering, just drop the mains voltage electrical laboratory in winter, the mains controled 217 Volts at 11 am, and because of this problem, the temperature Necessary for the solder can not be issued and the operation aborted

Part 2 : Next steep

◆ I await the arrival of samples from Japan via Italy, and it is possible that in the month of January I go to Holande for visit company that sells the product, to finalize the next generation of connectors kapton, covered with anisotropic adhesive, we have already received an offer price of EUR 4000 for 1000 pieces

Thank's and merry christmas

